

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	16	257/E23.188	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 16:18
L2	24	257/E23.009	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 16:18
L3	3584	257/712	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 16:19
L4	801	257/703	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 16:21
L5	3758	257/706	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 16:52
L6	2390	257/750	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 17:04
L7	4374	428/469	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 17:43

L8	4227	428/698	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 18:05
L9	7193	428/209	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 18:29
L10	2468	428/210	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 18:43
L11	6902	361/704	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 19:05
L12	865	228/121	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 19:12
L13	2	"20070160858"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/04 19:38
L15	2	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near alloy with ("Y" or "Sc" or "La" or "Ce" or "Nd" or "Sm" or "Gd" or "Tb" or "Dy" or "Er" or "Th" or "Sr") and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 19:42

L16	8	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near alloy same ("Y" or "Sc" or "La" or "Ce" or "Nd" or "Sm" or "Gd" or "Tb" or "Dy" or "Er" or "Th" or "Sr") and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 19:43
L17	15	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with alloy same ("Y" or "Sc" or "La" or "Ce" or "Nd" or "Sm" or "Gd" or "Tb" or "Dy" or "Er" or "Th" or "Sr") and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 19:43
L18	31	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with alloy same ("Y" or "Sc" or "La" or "Ce" or "Nd" or "Sm" or "Gd" or "Tb" or "Dy" or "Er" or "Th" or "Sr") and ("Al" or aluminum) with ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 19:43
L19	3497	257/700	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 19:56

L20	801	257/703	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 19:58
L21	24	257/E23.009	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/04 20:06
S1	1	"3893224".pn.	USPAT	OR	OFF	2008/07/03 21:31
S2	1	"6426154".pn.	USPAT	OR	OFF	2008/07/03 21:38
S3	1	"20070160858"	US-PGPUB; USPAT	OR	OFF	2008/07/03 21:58
S4	9	257/E23.188	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 21:59
S5	3484	257/712	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 22:00
S6	4307	428/469	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 22:04
S7	4167	428/698	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/03 22:17

S8	0	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near (plate or layer) with clad same ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	USPAT	OR	ON	2008/07/03 22:22
S9	0	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near (plate or layer) with clad and ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	USPAT	OR	ON	2008/07/03 22:23
S10	1	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near (plate or layer) and ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	USPAT	OR	ON	2008/07/03 22:24
S11	1	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with (plate or layer) and ("Al" or aluminum) near alloy with (pad) and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	USPAT	OR	ON	2008/07/03 22:24

S12	76	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with (plate or layer) and ("Al" or aluminum) near alloy and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	USPAT	OR	ON	2008/07/03 22:25
S13	2	"20040022029"	US-PGPUB; USPAT	OR	OFF	2008/07/04 19:39
S14	15	("5395679" "5621243" "5892279" "5920119" "5928768" "6033787" "6054762" "6055154" "6060772" "6201696" "6261703" "6309737" "6310775" "6483185" "6563709").PN. OR ("7019975").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 19:39
S15	0	"2000240580" or "2001194034"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 19:40
S16	3	"2000240580" or "2001194034"	JPO	OR	OFF	2008/07/04 19:40
S17	24	("4770953" "5011732" "5130498" "5145540" "5213877" "5529852" "5616421" "5675474").PN. OR ("6033787").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 20:38
S18	21	("3927815" "4672739" "4781970" "4979015").PN. OR ("5213877").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/07/04 20:55

S19	7105	428/209	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:05
S20	2429	428/210	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:07
S21	6663	361/704	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:22
S22	878498	(semiconductor or die or dice or chip or IC)	USPAT	OR	ON	2008/07/04 21:32
S23	36958	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) with alloy	USPAT	OR	ON	2008/07/04 21:32
S24	2	(semiconductor or die or dice or chip or IC) and (board or PCB or PWB or substrate) and ("Al" or aluminum) near alloy with ("Y" or "Sc" or "La" or "Ce" or "Nd" or "Sm" or "Gd" or "Tb" or "Dy" or "Er" or "Th" or "Sr") and ("Al" or aluminum) near ("Si" or silicon\$1) with (attach\$3 or solder\$3 or braz\$3)	USPAT	OR	ON	2008/07/04 21:33
S25	849	228/121	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:44
S26	786	257/703	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 21:59

S27	3645	257/706	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 22:07
S28	2333	257/750	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 22:10
S29	19	257/E23.009	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 22:41

11/4/08 8:09:10 PM

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